Product Change Notification

Change Notification #: **115243 - 00**

Change Title: **Select Intel® SSD 750 Series Products, PCN 115243-00, Transport Media, Packaging Update for Recycling Logo**

Date of Publication: **January 09, 2017**

Key Characteristics of the Change:

Transport Media

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	January 24, 2017

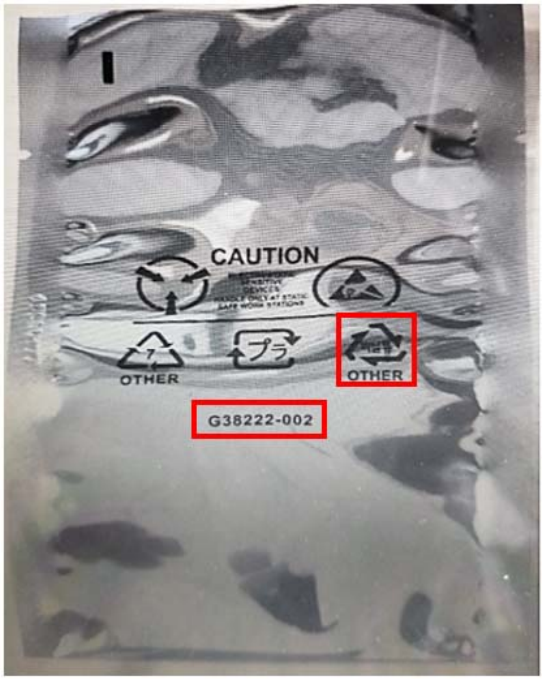
Description of Change to the Customer:

The Intel® SSD 750 Series SKUs listed in the Products Affected Table below will have the following changes to the Electrostatic Discharge (ESD) bag.

- Add South Korea Recycle Mark per regulatory 

- Changed the part number printed on the bag from G38222-001 to G38222-002

Please refer to the Current and New photos provided below:

Current ESD bag	New ESD bag
	

Customer Impact of Change and Recommended Action:

There is no change to the form, fit, function, quality or reliability of the product. This change affects the printing on the ESD bag to comply with regulatory requirements.

Customers should be aware of the changes to the ESD bag and take appropriate actions to accommodate the changes and avoid impact to their process.

Intel will attempt to deplete pre-conversion material before shipping post-conversion material but there is a possibility of Intel shipping mixed inventory. Therefore, customers will need to manage and migrate to the post-conversion material as soon as possible.

Milestone dates are estimates and subject to change based on business and operational conditions.

Please contact your local Intel Field Sales Representative if you have any further questions about these changes.

Products Affected / Intel Ordering Codes:

Marketing Name	Product Code	MM#
Intel® SSD 750 Series (400GB, 2.5in PCIe 3.0 x4, 20nm, MLC) Single Pack	SSDPE2MW400G4X1	944778
Intel® SSD 750 Series (800GB, 2.5in PCIe 3.0 x4, 20nm, MLC) Single Pack	SSDPE2MW800G4X1	944779
Intel® SSD 750 Series (1.2TB, 2.5in PCIe 3.0 x4, 20nm, MLC) Single Pack	SSDPE2MW012T4X1	944780
Intel® SSD 750 Series (400GB, 2.5in PCIe 3.0 x4, 20nm, MLC) Single Pack	SSDPE2MW400G4M2	949483
Intel® SSD 750 Series (800GB, 2.5in PCIe 3.0 x4, 20nm, MLC) Single Pack	SSDPE2MW800G4M2	949484
Intel® SSD 750 Series (1.2TB, 2.5in PCIe 3.0 x4, 20nm, MLC) Single Pack	SSDPE2MW012T4M2	949485

PCN Revision History:

Date of Revision:	**Revision Number:**	**Reason:**
January 9, 2017	00	Originally Published PCN

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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